

METHOD FOR FORMING PATTERNS FOR SEMICONDUCTOR DEVICES

Abstract of the Disclosure

5 A method for forming an electrically conductive layer having
predetermined patterns for semiconductor devices includes providing a
substrate, forming an insulation layer having OH functional groups on the
substrate, forming a patterned polymer layer on the insulation layer, etching the
insulation layer to create a patterned insulation layer which has the same
10 patterns as the patterned polymer layer, stripping the patterned polymer layer to
expose the patterned insulation layer, treating the patterned insulation layer with
a coupling agent which reacts with the OH functional groups, treating the
patterned insulation layer with a catalyst-containing solution in which the
catalyst reacts with the coupling agent, and depositing electrically conductive
15 material on the patterned insulation layer which is catalytically active.